

# RL78 Family

## FFT Library: Deployment Guide

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### Introduction

This document provides information for deploying FFT Library V. 1.01 Release 00 (the FFT library). Fast Fourier transform (FFT) is an algorithm that executes the discrete Fourier transform at high speed. The implementation developed in 1965 by James Cooley and John Tukey, now widely known as FFT, has contributed to the rapid advancement of digital signal processing applications.

The FFT library is provided in a version that has been tuned at the assembly language level to enable efficient processing on Renesas MCUs.

### Target Devices

RL78/G13, RL78/G14, RL78/G23

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## 1. Product Configuration

The product comprises the following items.

1. FFT Library V. 1.01 Release 00
2. FFT Library V. 1.01 Release 00: Deployment Guide (r20an0150ej0104\_rl78\_fft.pdf)  
Product No.: R0M7800LF0010RRC

The product comprises the files listed in Table 1.1.

**Table 1.1 FFT Library Configuration**

	Description
r20an0150ej0104_rl78_fft.pdf	Deployment guide (this document)
<b>Workspace (workspace)</b>	
<b>Documents (doc)</b>	
<b>English (en)</b>	
r20uw0099ej0102_fft.pdf	User's Manual
r20an0150ej0104_rl78_fft.pdf	Deployment guide (this document)
<b>Japanese (ja)</b>	
r20uw0099jj0102_fft.pdf	User's Manual
r20an0150jj0104_rl78_fft.pdf	Deployment guide
<b>CS+ for CA and CX (CS+ for CA)</b>	
<b>FFT library (lib)</b>	
libfft_rl78g13.lib	FFT library for RL78/G13 (assembler version), version 1.01
libfft_rl78g14.lib	FFT library for RL78/G14 (assembler version), version 1.01
r_fft_int16.h	FFT library header file
r_stdint.h	Type definition header file
<b>Sample program (sample)</b>	
rl78g14_fft	Sample CS+ for CA project (RL78/G14)
<b>CS+ for CC (CS+ for CC)</b>	
<b>FFT library (lib)</b>	
libfft_rl78g13.lib	FFT library for RL78/G13 (assembler version), version 1.01
libfft_rl78g14.lib	FFT library for RL78/G14 and RL78/G23 (assembler version), version 1.01
r_fft_int16.h	FFT library header file
r_stdint.h	Type definition header file
<b>Sample program (sample)</b>	
rl78g14_fft_ccrl	Sample CS+ for CC project (RL78/G14 and RL78/G23)

## 2. Library Functions

The FFT library supports the following library functions (APIs).

API	Description
R_rfft64_int16	16-bit fixed-point real-number FFT (64 points)
R_rfft128_int16	16-bit fixed-point real-number FFT (128 points)
R_rfft256_int16	16-bit fixed-point real-number FFT (256 points)

### 3. CS+ for CA and CX

#### 3.1 Limitations

The FFT library for the RL78/G13 uses the MCU's on-chip multiplier and divider/multiply-accumulator for multiply-accumulate operations. Therefore, it is necessary to ensure that the register values listed below are not changed within interrupt handlers implemented by the user. For information on the multiplier and divider/multiply-accumulator and related registers, refer to chapter 14, Multiplier and Divider/Multiply-Accumulator, in RL78/G13 User's Manual: Hardware.

##### Registers

- Multiplication/division data register A (L) (MDAL)
- Multiplication/division data register A (H) (MDAH)
- Multiplication/division data register B (L) (MDBL)
- Multiplication/division data register B (H) (MDBH)
- Multiplication/division data register C (L) (MDCL)
- Multiplication/division data register C (H) (MDCH)

##### Control register

- Multiplication/division control register (MDUC)

#### 3.2 Compiler Options

The library files are generated using the following compile options.

##### [Compile options]

```
-qx2 -common -mm -mi0 -ng
```

#### 3.3 Development Environment

The Renesas development environment consists of the items listed below.

Make sure to use the latest versions available when developing user applications.

##### [Software tools]

- Integrated development environment  
CS+ for CA, CX V3.00.01
- C compiler  
CA78K0R V1.71
- Debugger  
RL78 simulator; debugger library V3.00.00

### 3.4 ROM, RAM, and Stack Sizes

The ROM, RAM, and stack sizes of the various FFT library APIs are listed below (unit: bytes).

FFT library for RL78/G13:

API	ROM	RAM	Stack
R_rfft64_int16	1,261	0	66
R_rfft128_int16	1,513	0	66
R_rfft256_int16	2,019	0	66

FFT library for RL78/G14:

API	ROM	RAM	Stack
R_rfft64_int16	1,225	0	66
R_rfft128_int16	1,477	0	66
R_rfft256_int16	1,983	0	66

### 3.5 Section Information

The sections (segments) used by the various FFT library APIs are listed in the table below.

Section Name	Description	Section Attribute
@CODEL	Program	CSEG
@CNST	Constant data	CSEG MIRRORP

### 3.6 Library Performance

The processing times when calling the various library functions (APIs) are listed below.

FFT library for RL78/G13:

API	Time (System Clock = 32 MHz)
R_rfft64_int16	Approx. 0.4 ms
R_rfft128_int16	Approx. 0.9 ms
R_rfft256_int16	Approx. 1.9 ms

FFT library for RL78/G14:

API	Time (System Clock = 32 MHz)
R_rfft64_int16	Approx. 0.4 ms
R_rfft128_int16	Approx. 0.9 ms
R_rfft256_int16	Approx. 1.9 ms

### 3.7 Version Information

The version information for the library is stored as a character string in the `r_fft_a_version` variable. This variable can be accessed by means of the following extern declaration.

```
extern const char r_fft_a_version[];
```

The data stored in the libraries comprising the current product is shown below.

FFT library for RL78/G13:

```
const char r_fft_a_version[] =  
"FFT Library version 1.01 for RL78 Family (RL78G13) (Dec 07 2015, 17:29:14)";
```

FFT library for RL78/G14:

```
const char r_fft_a_version[] =  
"FFT Library version 1.01 for RL78 Family (RL78G14) (Dec 07 2015, 17:28:57)";
```

## 4. CS+ for CC

### 4.1 Limitations

The FFT library for the RL78/G13 uses the MCU's on-chip multiplier and divider/multiply-accumulator for multiply-accumulate operations. Therefore, it is necessary to ensure that the register values listed below are not changed within interrupt handlers implemented by the user. For information on the multiplier and divider/multiply-accumulator and related registers, refer to chapter 14, Multiplier and Divider/Multiply-Accumulator, in RL78/G13 User's Manual: Hardware.

Registers

- Multiplication/division data register A (L) (MDAL)
- Multiplication/division data register A (H) (MDAH)
- Multiplication/division data register B (L) (MDBL)
- Multiplication/division data register B (H) (MDBH)
- Multiplication/division data register C (L) (MDCL)
- Multiplication/division data register C (H) (MDCH)

Control register

- Multiplication/division control register (MDUC)

### 4.2 Compiler Options

The library files are generated using the following compile options.

[Compile options]

```
-asmopt=-mirror_source=common -memory_model=medium
```

### 4.3 Development Environment

The Renesas development environment consists of the items listed below.

Make sure to use the latest versions available when developing user applications.

[Software tools]

- Integrated development environment  
CS+ for CC V8.05.00
- C compiler  
CC-RL V1.10
- Debugger  
RL78 simulator



#### 4.4 ROM, RAM, and Stack Sizes

The ROM, RAM, and stack sizes of the various FFT library APIs are listed below (unit: bytes).

FFT library for RL78/G13:

API	ROM	RAM	Stack
R_rfft64_int16	1,260	0	68
R_rfft128_int16	1,512	0	68
R_rfft256_int16	2,018	0	68

FFT library for RL78/G14 and RL78/G23:

API	ROM	RAM	Stack
R_rfft64_int16	1,224	0	68
R_rfft128_int16	1,476	0	68
R_rfft256_int16	1,982	0	68

#### 4.5 Section Information

The sections (segments) used by the various FFT library APIs are listed in the table below.

Section Name	Description	Section Attribute
.textf	Program	.CSEG TEXTF
.const	Constant data	.CSEG CONST

#### 4.6 Library Performance

The processing times when calling the various library functions (APIs) are listed below.

FFT library for RL78/G13:

API	Time (System Clock = 32 MHz)
R_rfft64_int16	Approx. 0.4 ms
R_rfft128_int16	Approx. 0.9 ms
R_rfft256_int16	Approx. 1.9 ms

FFT library for RL78/G14 and RL78/G23:

API	Time (System Clock = 32 MHz)
R_rfft64_int16	Approx. 0.4 ms
R_rfft128_int16	Approx. 0.9 ms
R_rfft256_int16	Approx. 1.9 ms

## 4.7 Version Information

The version information for the library is stored as a character string in the `r_fft_a_version` variable. This variable can be accessed by means of the following extern declaration.

```
Extern const char r_fft_a_version[];
```

The data stored in the libraries comprising the current product is shown below.

FFT library for RL78/G13:

```
const char r_fft_a_version[] =  
"FFT Library version 1.01 for RL78 Family (RL78G13) (Dec 7 2015, 17:30:04)";
```

FFT library for RL78/G14 and RL78/G23:

```
const char r_fft_a_version[] =  
"FFT Library version 1.01 for RL78 Family (RL78G14) (Dec 7 2015, 17:29:42)";
```

**Revision History**

Rev.	Date	Description	
		Page	Summary
1.00	Mar. 31, 2012	—	First edition issued
1.01	Apr.1, 2014	—	Updated product configuration to match package version V. 1.00 Release 01. Added support for IAR Embedded Workbench.
1.02	Apr.1, 2015	2	Updated product configuration to match package version V. 1.00 Release 02.
1.03	Oct. 1, 2015	—	Changed CubeSuite+ to CS+ for CA and CX. Added support for CS+ for CC.
1.04	Apr. 13, 2021	—	Added RL78/G23 to CS+ for CC. Deleted IAR.

## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

### 2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

### 3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

### 4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

### 5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

### 6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

### 7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

### 8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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